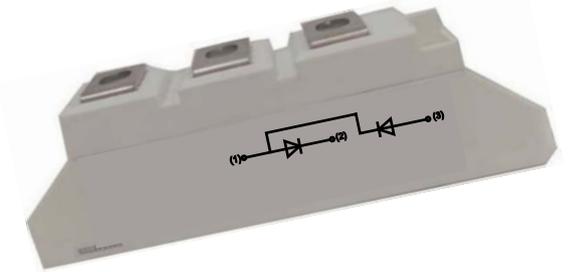


Diode Modules

MDD105M1Sxx

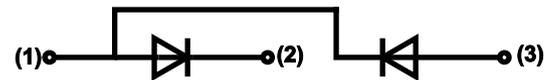
Features

- Blocking voltage: 1600 to 2200V
- Heat transfer through aluminum oxide DBC Ceramic isolated metal baseplate
- Industrial standard package
- Thick copper baseplate
- 2500 V_{RMS} isolating voltage



Typical Applications

- Power Supplies
- AC&DC Motor Drivers
- Bridge Circuits
- Welders
- Battery Supplier



Other circuit configurations also available on order

| Module Type | | |
|-------------|------------------|------------------|
| Type | V _{DRM} | V _{RSM} |
| MDD105M1S16 | 1600V | 1700V |
| MDD105M1S18 | 1800V | 1900V |
| MDD105M1S22 | 2200V | 2300V |

| Maximum Ratings | | | | |
|-------------------------------------|--------------------|---|----------|------------------|
| Parameters | Symbol | Test Conditions | Values | Unit |
| State the average current | I _{F(AV)} | Single phase ,half wave 180° conduction T _c =80°C | 105 | A |
| Surge forward current | I _{FSM} | t=10mS T _J =45°C | 3000 | A |
| Maximum I ² t for fusing | I ² t | t=10mS T _J =45°C | 45000 | A ² s |
| Isolation Breakdown Voltage(R.M.S) | V _{isol} | Ac.50Hz; R.M.S; 1min | 2500 | V |
| | | Ac.50Hz; R.M.S; 1sec | 3500 | V |
| Operating Junction Temperature | T _J | | -40~+150 | °C |
| Storage Temperature | T _{stg} | | -40~+125 | °C |
| Mounting Torque | M _t | To terminals(M5) | 3± 15% | Nm |
| | M _s | To heatsink(M6) | 5± 15% | |
| Module(Approximately) | Weight | | 100 | g |

Electrical Characteristics

| Parameters | Symbol | Test Conditions | Values | | | Unit |
|---|-----------|--|--------|------|------|---------------|
| | | | Min. | Typ. | Max. | |
| Maximum Forward voltage drop | V_{FM} | $T=25^{\circ}\text{C}$ $I_F=105\text{A}$ | – | 1.00 | 1.25 | V |
| Maximum Repetitive Peak Reverse Current | I_{RRM} | $T_J=25^{\circ}\text{C}$ $V_{RD}=V_{RRM}$ | – | – | 15 | μA |
| | | $T_J=150^{\circ}\text{C}$ $V_{RD}=V_{RRM}$ | – | – | 10 | mA |

Thermal Characteristics

| Parameters | Symbol | Test Conditions | Values | Unit |
|---|---------------|-----------------|--------|-----------------------------|
| Maximum internal thermal resistance, junction to case per leg | $R_{th(J-C)}$ | Per diode | 0.35 | $^{\circ}\text{C}/\text{W}$ |
| Typical thermal resistance, case to heatsink per module | $R_{th(C-S)}$ | Module | 0.10 | $^{\circ}\text{C}/\text{W}$ |

Performance Curves

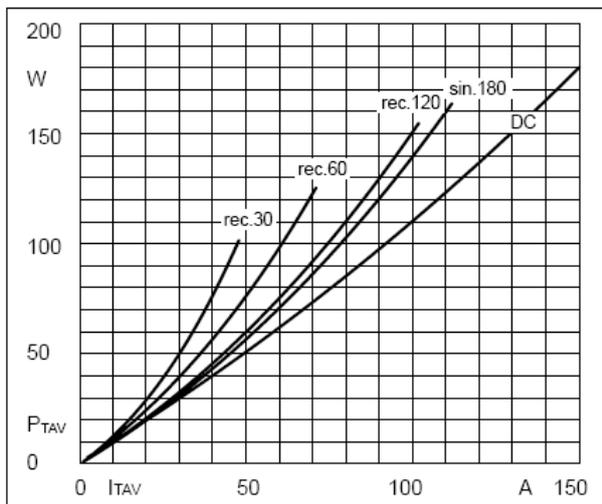


Fig1. Power dissipation

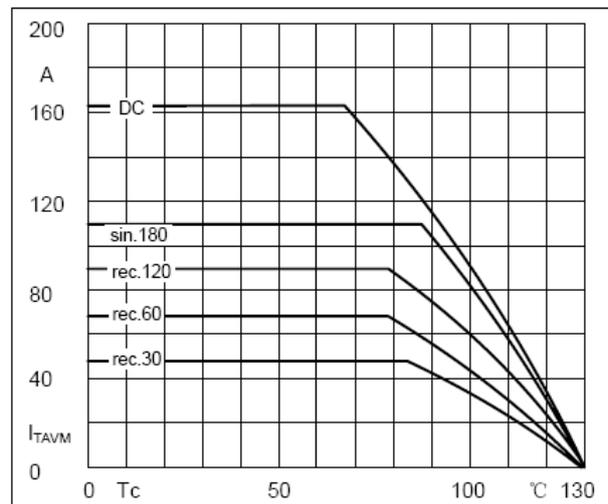


Fig2. Forward Current Derating Curve

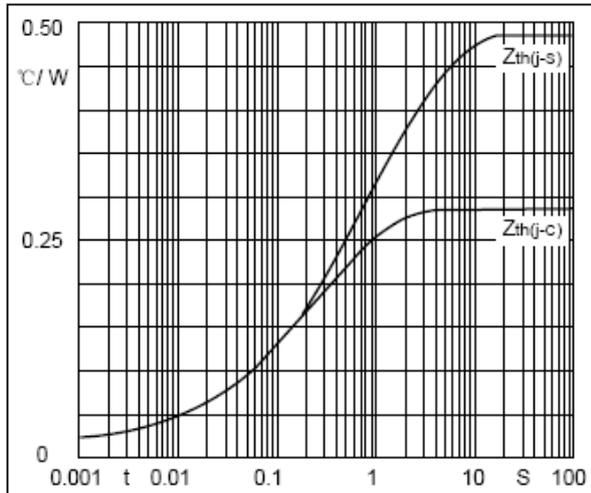


Fig3. Transient thermal impedance

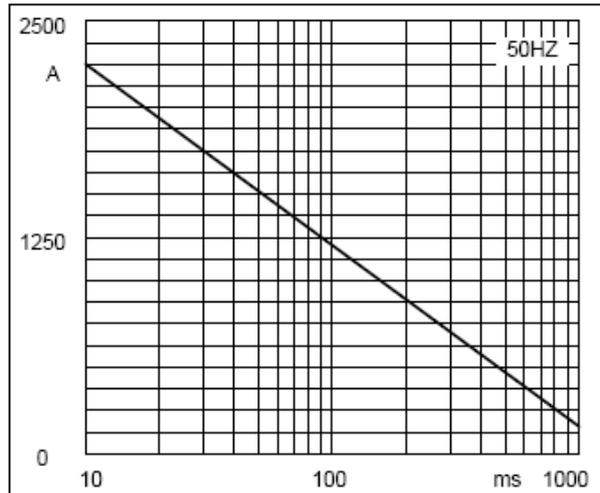


Fig4. Max Non-Repetitive Forward Surge Current

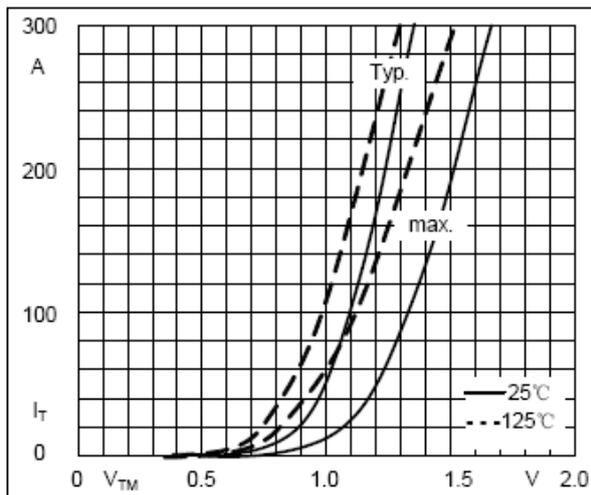


Fig5. Forward Characteristics

Ordering Information Table

Device Code

| | | | |
|-----|-----|-----|----|
| MDD | 105 | M1S | 16 |
|-----|-----|-----|----|

① ② ③ ④

- ① Diode power module
- ② Maximum average forward current, A
- ③ Package Size & type code
- ④ Voltage code 1600v

PACKAGE OUTLINE INFORMATION

Dimensions in mm

